



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



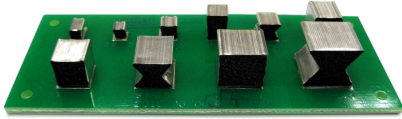
## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





## SMD METALLIZED FILM-OVER-FOAM GROUNDING CONTACT

Laird's SMD (Surface Mount Device) Grounding Contact is a foam cored contact with a metallized polyimide film outer covering. It is used for circuit grounding of SMT (Surface Mount Technology) devices. These contacts are designed to be solder reflow compatible, and are suitable for automatic processing.

### FEATURES

- Sn / Cu Plated PI Film outer layer
- Polymeric Foam Core
- Soft SMD contacts are RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Reflow tunnel compatible to 260° C
- Patent Pending
- UL94 HB Flammability Rating

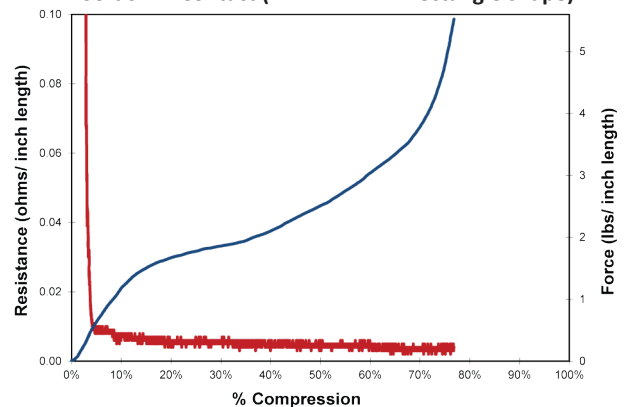
### MARKETS

- Cabinet applications
- LCD and Plasma TV
- Medical equipment
- Servers
- Printers
- Automotive
- Laptop computers and tablets
- Networking equipment
- Desktop computers
- Telecommunications cabinets

Item	Unit	Value	Test Method
Z-Axis Resistance			Laird Internal
Before Reflow	Ω	<0.06	
After Reflow	Ω	<0.10	
Flammability		PASS	UL 94 HB*
Solder Adhesion Strength (Contact to PCB)	kgf	>0.8	Laird Internal
Hardness (Shore A)	durometer	<20	ASTM D 2240
Compression Set	%	<15	ASTM D3574 Test D
Operation Temperature	°C	-40° to 70°	
Restricted Substances		RoHS Compliant Halogen Free	

\* UL file number E170327, UL designation code HB 026

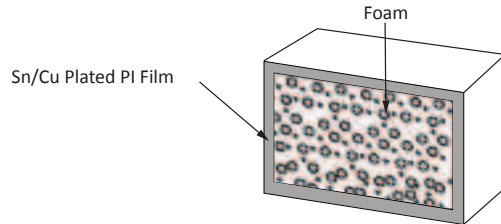
**Force/Displacement/Resistance Graph of Laird  
Soft SMD Contact (7 mm x 7 mm rectangle shape)**



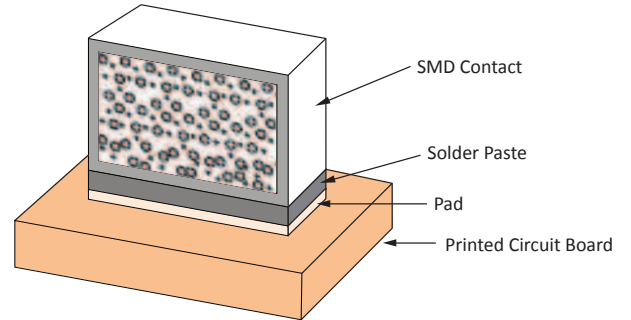
Americas: +1.800.323.3757  
LHP.Sales@lairdtech.com  
Europe: +46.8.555.722.00  
LHP.Sales@lairdtech.com  
Asia: +86.10.5933.3682  
LHP-ChinaSales@lairdtech.com

# Soft SMD Grounding Contacts Metallized Film-over-Foam

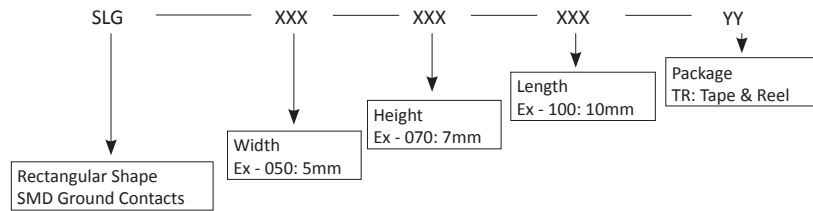
## PRODUCT COMPOSITION



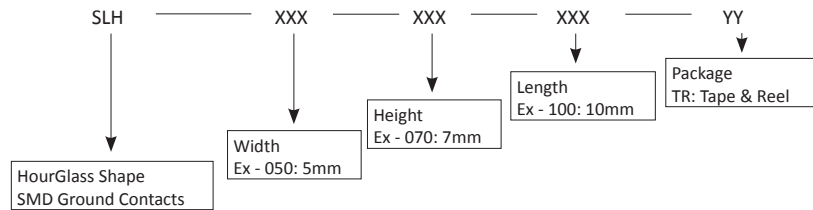
## PRODUCT APPLICATION



## PART NUMBER STRUCTURE



Example: "SLG-050-070-100-TR" for rectangular shape, 5mm in width, 7mm in height and 10mm length in Tape & Reel.



Example: "SLH-050-070-100-TR" for hourglass shape, 5mm in width, 7mm in height and 10mm length in Tape & Reel.

## TYPICAL REFLOW CONDITIONS

	Temperature Profile	Condition	
		Temperature	Time
A	Preheating Stage	Room Temp. -170°C	125 sec.
B	Heating / Soaking Stage	170-217°C	100 sec.
C	Reflow Stage	217-Peak Temp. (~260°C Max)	50 sec.
D	Cooling Stage	Peak Temp. - Room Temp.	>60 sec.

Product is available in tape and reel packaging

Values presented have been determined by standard test methods and are typical values not to be used for specification purposes.

EMI-DS-FOF-SOFT-SMD 070215

Any information furnished by Laird and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird materials rests with the end user, since Laird and its agents cannot be aware of all potential uses. Laird makes no warranties as to the fitness, merchantability or suitability of any Laird materials or products for any specific or general uses. Laird, Laird Technologies, Inc or any of its affiliates or agents shall not be liable for incidental or consequential damages of any kind. All Laird products are sold pursuant to the Laird Technologies' Terms and Conditions of sale in effect from time to time, a copy of which will be furnished upon request. © Copyright 2015 Laird Technologies, Inc. All Rights Reserved. Laird, Laird Technologies, the Laird Logo, and other marks are trademarks or registered trademarks of Laird Technologies, Inc. or an affiliate company thereof. Other product or service names may be the property of third parties. Nothing herein provides a license under any Laird or any third party intellectual property rights.